

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(conductive adj contact adj pad) and substrate and dielectric and opening and (contact adj pad) and (solder adj paste).clm.	US-PGPUB	OR	ON	2007/02/09 14:37
S1	0	("10798540").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/09 14:35
S2	228	(conductive adj contact adj pad) and (dielectric) and (regions)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 14:40
S3	11	(conductive adj contact adj pad) and (dielectric) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 18:13
S4	260	(contact adj pad) and (dielectric) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:45
S5	503	(contact adj pad) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 19:54
S6	0	S5 and ((solder near paste) with (opening and via and trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 19:56
S7	47	S5 and ((solder near paste) with (opening via trench))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:28

## EAST Search History

S8	503	(contact adj pad) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:29
S9	28	S8 and ((solder near paste) and (second adj substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:30
S10	65	(contact adj pad) and (dielectric) and (solder near paste) and (second adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:34
S11	49	S10 and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 13:35
S12	185	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:47
S13	5194150	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit) or (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:48
S14	185	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated circuit) and (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:50
S15	131	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated adj circuit) and (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:50

## EAST Search History

S16	2	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated adj circuit) and (integrated adj circuit adj package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 15:51
S17	28312	flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:44
S19	825	S17 and (contact adj pads) and dielectric and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:47
S20	18	S19 and (solder adj paste) with (opening via trench hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:46
S21	548	S19 and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:48
S22	82	S21 and (solder near2 (wet wettable))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 16:49
S23	2	("6322903").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:41
S27	776	S17 and (bond adj pads) and dielectric and openings	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 18:48

## EAST Search History

S28	3220	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/27 15:47
S29	10712	(contact adj pad) and (dielectric or insulat\$5) and (opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 13:21
S30	4265	S29 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/03 13:22
S31	2627	S30 and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S32	10725	(contact adj pad) and (dielectric or insulat\$5) and (opening)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S33	4269	S32 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S34	2630	S33 and (integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S35	1312	S34 and (flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/04 15:27
S36	2	("4256532"   "5880017").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/04 15:39

## EAST Search History

S37	2	("5341564"   "5952718").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/18 10:48
S38	20	("2014524"   "2774747"   "3401126"   "3429040"   "4113981"   "4442966"   "5046415"   "5056296"   "5074947"   "5196371"   "5237130"   "5539153"   "5611140"   "5667884"   "5879761"   "5924622").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/18 12:38
S39	572	(contact adj pad) and (solder near2 (wet table))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 16:19
S40	34	S39 and ((solder near paste) and (second adj substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 16:19
S41	156	(contact adj pad) and (dielectric) and (solder near2 (wet table)) and (openings) and (integrated adj circuit) and (integrated circuit package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 16:20
S42	13	("3971610"   "4157932"   "4442966"   "4554033"   "4587038"   "4640981"   "4719140"   "4764804"   "4818728"   "4922321"   "5001302"   "5068714"   "5074947").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/02/08 14:27
S43	33	("1067415"   "3002847"   "3458925"   "3569607"   "3719981"   "4369376"   "4489923"   "4545610"   "4759490"   "4832255"   "4898320"   "4906823"   "5022580"   "5024372"   "5046161"   "5105537"   "5108027"   "5118027"   "5118029"   "5133495"   "5139610"   "5162257"   "5217597"   "5219117"   "5261593"   "5271548"   "5307983"   "5317438"   "5323947"   "5346118").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/02/08 14:28

## EAST Search History

S44	24	("3320658"   "3396894"   "3458925"   "3871015"   "4050621"   "4064552"   "4205099"   "4273859"   "4354629"   "4545610"   "4604644"   "4605153"   "4739917"   "4761881"   "4774633"   "4914551"   "4914814"   "4950623"   "4967950"   "5048747"   "5057969").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/02/08 14:37
S45	264	(conductive adj contact adj pad) and (dielectric) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 14:40
S46	3751	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 17:32
S47	11	S46 and (conductive adj contact adj pad) and (dielectric) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 17:33
S48	223	S46 and (contact adj pad) and (dielectric) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:06
S49	1754	(438/108).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 17:37
S50	85	S49 and (contact adj pad) and (dielectric) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 17:42
S51	1698	(438/118).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 17:42

## EAST Search History

S52	105	S51 and (contact adj pad) and (dielectric) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 17:47
S53	173	S49 and (contact adj pad) and (dielectric) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 17:42
S54	409	(438/119).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 17:47
S55	36	S54 and (contact adj pad) and (dielectric) and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 17:47
S56	1659	(438/613).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:07
S57	34	S56 and (contact adj pad) and (dielectric) and (solder) and wettable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:07
S58	2250	(438/614).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:13
S59	26	S58 and (contact adj pad) and (dielectric) and (solder) and (wett\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:15

## EAST Search History

S60	301	(438/615).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:15
S61	26	S59 and (contact adj pad) and (dielectric) and (solder) and (wett\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:16
S62	145	(438/616).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:16
S63	13	S60 and (contact adj pad) and (dielectric) and (solder) and (wett\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:17
S64	26	S61 and (contact adj pad) and (dielectric) and (solder) and (wett\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:17
S65	6	S62 and (contact adj pad) and (dielectric) and (solder) and (wett\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:18
S66	503	(438/617).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:18
S67	10	S66 and (contact adj pad) and (dielectric) and (solder) and (wett\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/08 18:20

## EAST Search History

S68	4	(("20040087057") or ("5611140")). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/02/08 18:21
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